# GIGABYTE unveils innovative B800 series motherboards at CES 2025



At the Consumer Electronics Show (CES) 2025, held in Las Vegas, GIGABYTE, a prominent player in the global computer hardware market, introduced its latest generation of motherboards, the Intel® B860 and AMD B850 series. Unveiled on January 8, 2025, these new models are engineered to maximise the capabilities of the latest Intel® Core™ Ultra and AMD Ryzen™ processors through the integration of advanced AI technology and a commitment to user-friendly design.

The B800 series motherboards are designed to enhance both gaming and PC-building experiences, boasting a range of features aimed at mainstream PC gamers. GIGABYTE’s robust technological upgrades include all-digital power management and improved thermal design. The new series highlights a significant achievement, with GIGABYTE claiming the largest market share in the X870 series motherboards, notably due to their compatibility with the AMD Ryzen™ 5 7000 and 9000 series X3D processors.

A notable aspect of the B800 series is its inclusion of the AI suite known as D5 Bionics Corsa. This system merges software, hardware, and firmware to elevate DDR5 memory performance significantly—up to 8600MT/s for AMD B850 models and an impressive 9466MT/s for Intel® B860 motherboards. The series also features AI SNATCH, an exclusive AI software tool that simplifies performance enhancement with just a few clicks. The PCBs (Printed Circuit Boards) incorporate AI-driven design, which minimises signal reflection and maximises performance across multiple circuit layers.

To further cater to high-intensity gaming and multitasking, GIGABYTE has introduced the HyperTune BIOS. This advanced feature incorporates AI-driven technologies to refine the Memory Reference Code specifically for Intel® B860 motherboards. Additionally, for those utilising AMD Ryzen™ 9000 series X3D processors, the B850 motherboards benefit from a dedicated X3D Turbo mode that optimises core counts to enhance gaming efficiency.

Cooling effectiveness is another critical development in the B800 series. The motherboards are equipped with a premium thermal solution that features a heatsink capable of increasing cooling surface area up to four times, supported by heat pipes and high thermal conductivity pads to ensure superior cooling performance under intensive workloads.

User-friendly installations have also been a focal point for GIGABYTE, which included numerous DIY-friendly innovations such as PCIe EZ-Latch Plus, M.2 EZ-Latch Click, and WIFI EZ-PLUG onboard options. These enhancements aim to simplify the building process for users.

In addition to the high-end AORUS PRO and ELITE models, GIGABYTE presented its GAMING(X) and EAGLE series, alongside the ICE series. The ICE series, characterised by its all-white aesthetic, features pure white components including PCB, memory DIMM slots, PCIe slots, connectors, and a debug port, catering to enthusiasts focused on aesthetic cohesion in their builds.

GIGABYTE also ensured compatibility with its AI TOP utility through the B850 AI TOP model, which provides local AI fine-tuning for productivity-focused users. The unveiling of the B800 series at CES 2025 underscores GIGABYTE's commitment to delivering cutting-edge solutions that leverage AI technology, enhancing both performance and user experience in the burgeoning landscape of gaming and PC hardware.

Source: [Noah Wire Services](https://www.noahwire.com)

## Bibliography

1. <https://www.gigabyte.com/Press/News/2254> - Corroborates the introduction of Intel® B860 and AMD B850 series motherboards at CES 2025, and their design to maximize the capabilities of the latest Intel® Core™ Ultra and AMD Ryzen™ processors.
2. <https://www.techpowerup.com/forums/threads/gigabyte-redefines-intel-and-amd-b800-series-motherboards-performance-with-ai-technology-at-ces-2025.330801/> - Supports the integration of advanced AI technology and user-friendly design in the B800 series motherboards.
3. <https://www.gigabyte.com/Press/News/2254> - Details the features aimed at mainstream PC gamers, including all-digital power management and improved thermal design.
4. <https://www.techpowerup.com/forums/threads/gigabyte-redefines-intel-and-amd-b800-series-motherboards-performance-with-ai-technology-at-ces-2025.330801/> - Confirms GIGABYTE's achievement of the largest market share in the X870 series motherboards due to compatibility with AMD Ryzen™ 5 7000 and 9000 series X3D processors.
5. <https://www.gigabyte.com/Press/News/2254> - Explains the AI suite D5 Bionics Corsa and its role in elevating DDR5 memory performance.
6. <https://www.techpowerup.com/forums/threads/gigabyte-redefines-intel-and-amd-b800-series-motherboards-performance-with-ai-technology-at-ces-2025.330801/> - Describes the AI SNATCH software tool and its function in simplifying performance enhancement.
7. <https://www.gigabyte.com/Press/News/2254> - Details the AI-driven PCB design and its impact on minimizing signal reflection and maximizing performance.
8. <https://www.gigabyte.com/Motherboard/B850-AI-TOP> - Explains the HyperTune BIOS and its AI-driven technologies for refining the Memory Reference Code on Intel® B860 motherboards.
9. <https://www.gigabyte.com/Press/News/2254> - Describes the X3D Turbo mode on AMD B850 series motherboards for enhancing gaming efficiency with AMD Ryzen™ 9000 series X3D processors.
10. <https://www.gigabyte.com/Press/News/2254> - Details the premium thermal solution, including the heatsink, heat pipes, and high thermal conductivity pads for superior cooling performance.
11. <https://www.gigabyte.com/Press/News/2254> - Highlights the user-friendly installations with DIY-friendly innovations such as PCIe EZ-Latch Plus, M.2 EZ-Latch Click, and WIFI EZ-PLUG onboard options.
12. <https://news.google.com/rss/articles/CBMi4gFBVV95cUxQelVza1c3d3ZoVUVwOVJTZnBOMXg4YzdWQjlmVnZHQTFtYVBvTnFnQklDbnNXanlyTGpQRGNDdFQ1UmNDeHF6V0VpM1JrRGhIVG5ucUFUNGh5SWNsT3NZcnhWS3RKckd1TUR5ZGxoOE9GN1YyM3ZBVUNDdVAxdm13MndsUEU5b2Q2RGpMXzlRLTNsbzhLY29oVEtxUHBOaWZoS0tLamdpQ0pZNS1nVTVSQmpVNXhNU1ZIal9YQm5NM2JUTl9TMHJLSUJoRENHZ3VkVUhCT096Z08tQjdBeWQzWHpB?oc=5&hl=en-US&gl=US&ceid=US:en> - Please view link - unable to able to access data